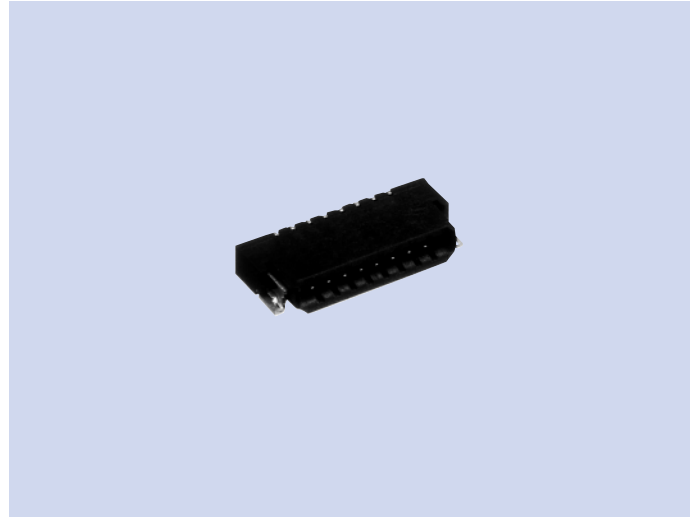


# 1.00mm Density NON-ZIF FPC Connectors

## CEM-B80 Series

### FEATURES

1. Surface packaging (SMD) type connector for flexible PCB (FPC).
2. Thin non-ZIF system.
3. Double-sided contact system with 1mm pitch.



### HOW TO ORDER

**B80-008-05 0-HJGA**

1
2
3
4
5

- 1 Series No.
- 2 No. of contacts (008 : 8pins)
- 3 Housing material (05 : Nylon resin)
- 4 UL grade (0 : UL94V-0)
- 5 Supplementary symbol

### SPECIFICATIONS

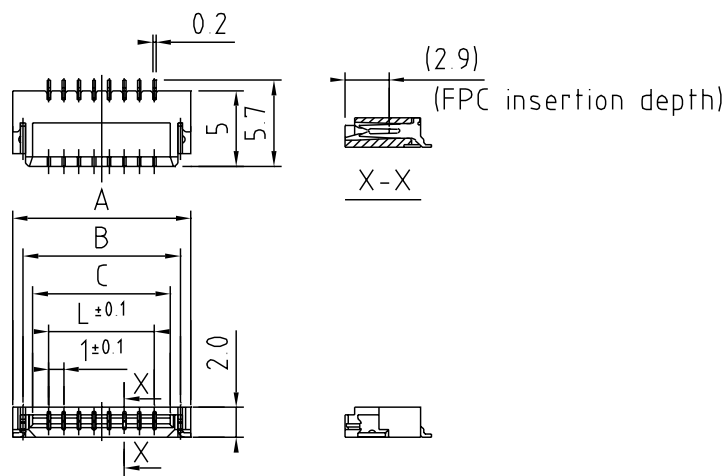
#### ELECTRICAL CHARACTERISTICS & MECHANICAL CHARACTERISTICS

Rated Voltage	50V AC (rms)
Rated Current	0.5A
Withstanding Voltage	500V AC (rms) 1minute
Insulation Resistance	100MΩ min. (at 500V DC)
Contact Resistance	30mΩ max.
Applicable FPC Thickness	0.3±0.05mm

### MATERIAL & FINISH

Component Parts	Material	Finish
Housing	Nylon resin	—
Contact	Copper Alloy	Solder plating
Wing	Copper Alloy	Solder plating

**DIMENSIONS**



Unit : mm

No. of Contacts	Part No.	Measurement			
		L	A	B	C
4	B80-004-050-HJGE	3	7.8	6.4	5.1
8	B80-008-050-HJGA	7	11.8	10.4	9.1